

### LM5025

# **Active Clamp Voltage Mode PWM Controller**

## **General Description**

The LM5025 PWM controller contains all of the features necessary to implement power converters utilizing the Active Clamp / Reset technique. The device can be configured to control either a P-Channel clamp switch or an N-Channel clamp switch. With the active clamp technique, higher efficiencies and greater power densities can be realized compared to conventional catch winding or RDC clamp / reset techniques. Two control outputs are provided, the main power switch control (OUT\_A) and the active clamp switch control (OUT\_B). The active clamp output can be configured for either a guaranteed overlap time (for P-Channel switch applications) or a quaranteed deadtime (for N Channel applications). The two internal compound gate drivers parallel both MOS and Bipolar devices, providing superior gate drive characteristics. This controller is designed for high-speed operation including an oscillator frequency range up to 1MHz and total PWM and current sense propagation delays less than 100ns. The LM5025 includes a high-voltage start-up regulator that operates over a wide input range of 13V to 90V. Additional features include: Line Under Voltage Lockout (UVLO), softstart, oscillator UP/DOWN sync capability, precision reference and thermal shutdown.

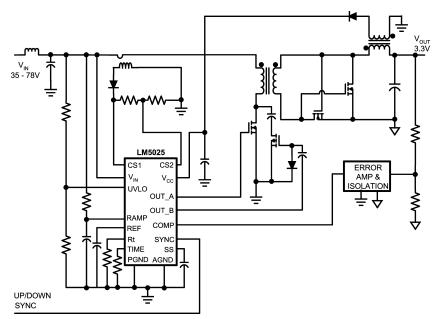
#### **Features**

- Internal Start-up Bias Regulator
- 3A Compound Main Gate Driver
- Programmable Line Under-Voltage Lockout (UVLO) with Adjustable Hysteresis
- Voltage Mode Control with Feed-Forward
- Adjustable Dual Mode Over-Current Protection
- Programmable Overlap or Deadtime between the Main and Active Clamp Outputs
- Volt x Second Clamp
- Programmable Soft-start
- Leading Edge Blanking
- Single Resistor Programmable Oscillator
- Oscillator UP / DOWN Sync Capability
- Precision 5V Reference
- Thermal Shutdown

#### **Packages**

- TSSOP-16
- LLP-16 (5x5 mm) Thermally Enhanced

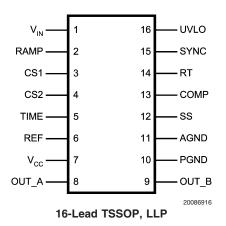
## **Typical Application Circuit**



Simplified Active Clamp Forward Power Converter

2008690

# **Connection Diagram**



# **Ordering Information**

Order Number	Package Type	NSC Package Drawing	Supplied As
LM5025MTC	TSSOP-16	MTC-16	92 Units per anti-static tube
LM5025MTCX	TSSOP-16	MTC-16	2500 Units on Tape and Reel
LM5025SD	LLP-16	SDA-16A	1000 Units on Tape and Reel
LM5025SDX	LLP-16	SDA-16A	4500 Units on Tape and Reel

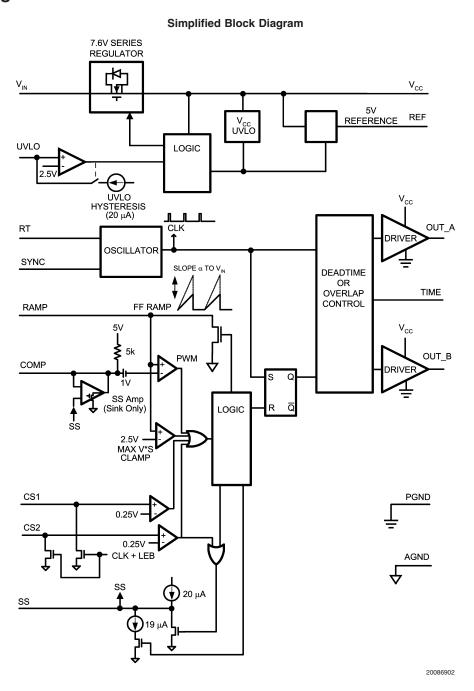
## **Pin Description**

PIN	NAME	DESCRIPTION	APPLICATION INFORMATION		
1	V <sub>IN</sub>	Source Input Voltage	Input to start-up regulator. Input range 13V to 90V,		
			with transient capability to 100V.		
2	RAMP	Modulator ramp signal	An external RC circuit from Vin sets the ramp slope.		
			This pin is discharged at the conclusion of every		
			cycle by an internal FET, initiated by either the		
			internal clock or the V*Sec Clamp comparator.		
3	CS1	Current sense input for cycle-by-cycle limiting	If CS1 exceeds 0.25V the outputs will go into		
			Cycle-by-Cycle current limit. CS1 is held low for		
			50ns after OUT_A switches high providing leading		
			edge blanking.		
4	CS2	Current sense input for soft restart	If CS2 exceeds 0.25V the outputs will be disabled		
			and a softstart commenced. The soft-start capacitor		
			will be fully discharged and then released with a		
			pull-up current of 1µA. After the first output pulse		
			(when SS =1V), the SS charge current will revert		
			back to 20µA. CS2 is held low for 50ns after OUT_A		
			switches high, providing leading edge blanking.		
5	TIME	Output overlap/Deadtime control	An external resistor (R <sub>SET</sub> ) sets either the overlap		
			time or dead time for the active clamp output. An		
			R <sub>SET</sub> resistor connected between TIME and GND		
			produces in-phase OUT_A and OUT_B pulses with		
			overlap. An R <sub>SET</sub> resistor connected between TIME		
			and REF produces out-of-phase OUT_A and OUT_B		
			pulses with deadtime.		
6	REF	Precision 5 volt reference output	Maximum output current: 10mA Locally decouple		
			with a 0.1µF capacitor. Reference stays low until the		
			line UVLO and the V <sub>CC</sub> UV comparators are		
			satisfied.		

# Pin Description (Continued)

PIN	NAME	DESCRIPTION	APPLICATION INFORMATION
7	V <sub>CC</sub>	Output from the internal high voltage start-up	If an auxiliary winding raises the voltage on this pin
		regulator. The $V_{\rm CC}$ voltage is regulated to	above the regulation setpoint, the internal start-up
		7.6V.	regulator will shutdown, reducing the IC power
			dissipation.
8	OUT_A	Main output driver	Output of the main switch PWM output gate driver.
			Output capability of 3A peak sink current.
9	OUT_B	Active Clamp output driver	Output of the Active Clamp switch gate driver.
			Capable of 1.25A peak sink current
10	PGND	Power ground	Connect directly to analog ground.
11	AGND	Analog ground	Connect directly to power ground. For the LLP
			package option the exposed pad is electrically
			connected to AGND.
12	SS	Soft-start control	An external capacitor and an internal 20µA current
			source set the softstart ramp. The SS current source
			is reduced to 1uA initially following a CS2
			over-current event or an over temperature event.
13	COMP	Input to the Pulse Width Modulator	An internal 5K $\Omega$ resistor pull-up is provided on this
			pin. The external opto-coupler sinks current from
			COMP to control the PWM duty cycle.
14	RT	Oscillator timing resistor pin	An external resistor connected from RT to ground
			sets the internal oscillator frequency.
15	SYNC	Oscillator UP/DOWN synchronization input	The internal oscillator can be synchronized to an
			external clock with a frequency 20% lower than the
			internal oscillator's free running frequency. There is
			no constraint on the maximum sync frequency.
16	UVLO	Line Under-Voltage shutdown	An external voltage divider from the power source
			sets the shutdown comparator levels. The
			comparator threshold is 2.5V. Hysteresis is set by an
			internal current source (20µA) that is switched on or
			off as the UVLO pin potential crosses the 2.5V
			threshold.

# **Block Diagram**



## **Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

 $\begin{array}{lll} V_{\text{IN}} \text{ to GND} & -0.3 \text{V to } 100 \text{V} \\ V_{\text{CC}} \text{ to GND} & -0.3 \text{V to } 16 \text{V} \\ \text{CS1, CS2 to GND} & -0.3 \text{ to } 1.00 \text{V} \\ \text{All other inputs to GND} & -0.3 \text{ to } 7 \text{V} \\ \end{array}$ 

ESD Rating (Note 2)

Human Body Model 2kV

Machine Model 200V

Storage Temperature Range -55°C to 150°C

Junction Temperature 150°C

## **Operating Ratings** (Note 1)

 $V_{IN}$  Voltage 13 to 90V External Voltage Applied to  $V_{CC}$  8 to 15V Operating Junction Temperature -40°C to +125°C

#### **Electrical Characteristics**

Specifications with standard typeface are for  $T_J = 25^{\circ}C$ , and those with **boldface** type apply over full **Operating Junction Temperature range**.  $V_{IN} = 48V$ ,  $V_{CC} = 10V$ ,  $RT = 31.3k\Omega$ ,  $R_{SET} = 27.4k\Omega$ ) unless otherwise stated (Note 3)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Startup Re	gulator					
V <sub>CC</sub> Reg	V <sub>CC</sub> Regulation	No Load	7.3	7.6	7.9	V
	V <sub>CC</sub> Current Limit	(Note 4)	20	25		mA
I-V <sub>IN</sub>	Startup Regulator Leakage (external Vcc Supply)	V <sub>IN</sub> = 100V		165	500	μА
	Shutdown Current (lin)	UVLO = 0V		350	450	μΑ
V <sub>CC</sub> Suppl	у					
	V <sub>CC</sub> Under-voltage Lockout Voltage (positive going V <sub>cc</sub> )		V <sub>CC</sub> Reg - 220mV	V <sub>CC</sub> Reg - 120mV		V
	V <sub>CC</sub> Under-voltage Hysteresis		1.0	1.5	2.0	V
	V <sub>CC</sub> Supply Current (I <sub>CC</sub> )	C <sub>gate</sub> = 0			4.2	mA
Reference	Supply					
$V_{REF}$	Ref Voltage	I <sub>REF</sub> = 0 mA	4.85	5	5.15	V
	Ref Voltage Regulation	I <sub>REF</sub> = 0 to 10mA		25	50	mV
	Ref Current Limit		10	20		mA
Current Li	mit			,		•
CS1 Prop	CS1 Delay to Output	CS1 Step from 0 to 0.4V Time to onset of OUT Transition (90%) C <sub>gate</sub> = 0		40		ns
CS2 Prop	CS2 Delay to Output	CS2 Step from 0 to 0.4V Time to onset of OUT Transition (90%) C <sub>gate</sub> = 0		50		ns
	Cycle by Cycle Threshold Voltage (CS1)		0.22	0.25	0.28	V
	Cycle Skip Threshold Voltage (CS2)	Resets SS capacitor; auto restart	0.22	0.25	0.28	V
	Leading Edge Blanking Time			50		ns
	CS Sink Impedance (clocked)	I <sub>CS</sub> = 10mA		30	50	Ω

## **Electrical Characteristics** (Continued)

Specifications with standard typeface are for  $T_J = 25\,^{\circ}\text{C}$ , and those with **boldface** type apply over full **Operating Junction Temperature range**.  $V_{IN} = 48\,\text{V}$ ,  $V_{CC} = 10\,\text{V}$ ,  $RT = 31.3\,\text{k}\Omega$ ,  $R_{SET} = 27.4\,\text{k}\Omega$ ) unless otherwise stated (Note 3)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Soft-Start						
	Soft-start Current		17	22	27	μΑ
	Source Normal					
	Soft-start Current		0.5	1	1.5	μΑ
	Source following a					
	CS2 event					
Oscillator	Τ	T 05:0	400		1	
	Frequency1	$T_A = 25^{\circ}C$	180	200	220	kHz
	F	$T_J = T_{low}$ to $T_{high}$	175	500	225	1.1.1=
	Frequency2	RT = 10.4KΩ	500	580	660	kHz
	Sync threshold			2	100	V
	Min Sync Pulse Width		100		100	ns
	Sync Frequency		160			kHz
DWM 0	Range					
PWM Com	•	00MD -+ 5V +- 0V		40		T
	Delay to Output	COMP step 5V to 0V Time to onset of OUT_A		40		ns
		transition low				
	Duty Cycle Range	transition low	0		80	%
	COMP to PWM Offset		0.7	1	1.3	/° V
			4.3	<u>'</u>	5.9	V
	COMP Open Circuit Voltage		4.3		5.9	V
	COMP Short Circuit	COMP = 0V	0.6	1	1.4	mA
	Current	COIVIF = 0V	0.6	'	1.4	IIIA
Volt x Sec	ond Clamp		L			
VOIL X OCO	Ramp Clamp Level	Delta RAMP measured	2.4	2.5	2.6	V
	Tramp Gramp 2010.	from onset of OUT_A to		0		
		Ramp peak.				
		COMP = 5V				
UVLO Shu	tdown		1		-	
	Undervoltage		2.44	2.5	2.56	V
	Shutdown Threshold					
	Undervoltage		16	20	24	μΑ
	Shutdown Hysteresis					
Output Se	ction					
	OUT_A High	MOS Device @ lout =		5	10	Ω
	Saturation	-10mA,				
	OUTPUT_A Peak	Bipolar Device @ Vcc/2		3		А
	Current Sink					
	OUT_A Low	MOS Device @ lout =		6	9	Ω
	Saturation	10mA,				
	OUTPUT_A Rise Time	C <sub>gate</sub> = 2.2nF		20		ns
	OUTPUT_A Fall Time	C <sub>gate</sub> = 2.2nF		15		ns
	OUT_B High	MOS Device @ lout =		10	20	Ω
	Saturation	-10mA,				
	OUTPUT_B Peak	Bipolar Device @ Vcc/2		1		А
	Current Sink					
	OUT_B Low	MOS Device @ lout =		12	18	Ω
	Saturation	10mA,				
	OUTPUT_B Rise Time	C <sub>gate</sub> = 1nF		20		ns

## **Electrical Characteristics** (Continued)

Specifications with standard typeface are for  $T_J = 25\,^{\circ}\text{C}$ , and those with **boldface** type apply over full **Operating Junction Temperature range**.  $V_{IN} = 48\,\text{V}$ ,  $V_{CC} = 10\,\text{V}$ ,  $RT = 31.3\,\text{k}\Omega$ ,  $R_{SET} = 27.4\,\text{k}\Omega$ ) unless otherwise stated (Note 3)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
	OUTPUT_B Fall Time	C <sub>gate</sub> = 1nF		15		ns
Output Tir	ning Control					
	Overlap Time	$R_{SET}$ = 38 kΩ connected to GND, 50% to 50% transitions	75	105	135	ns
	Deadtime	$R_{SET}$ = 29.5 k $\Omega$ connected to REF, 50% to 50% transitions	75	105	135	ns
Thermal S	hutdown					•
T <sub>SD</sub>	Thermal Shutdown Threshold			165		°C
	Thermal Shutdown Hysteresis			25		°C
Thermal R	esistance					
$\theta_{JA}$	Junction to Ambient	MTC Package		125		°C/W
		SDA Package		32		°C/W

**Note 1:** Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is intended to be functional. For guaranteed specifications and test conditions, see the Electrical Characteristics.

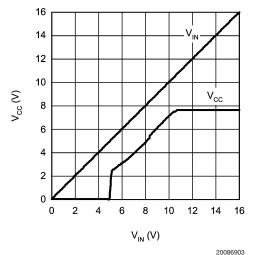
Note 2: For detailed information on soldering plastic TSSOP and LLP packages, refer to the Packaging Data Book available from National Semiconductor Corporation.

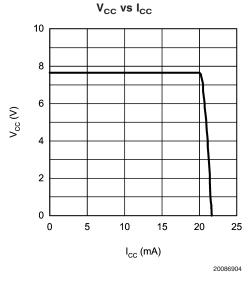
Note 3: All limits are guaranteed. All electrical characteristics having room temperature limits are tested during production with  $T_A = T_J = 25^{\circ}C$ . All hot and cold limits are guaranteed by correlating the electrical characteristics to process and temperature variations and applying statistical process control.

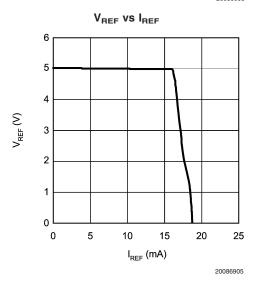
Note 4: Device thermal limitations may limit usable range.

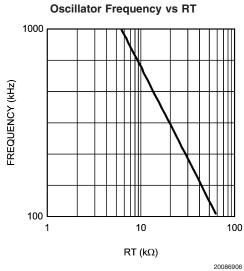
## **Typical Performance Characteristics**

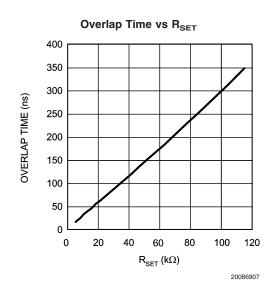
 $\rm V_{\rm CC}$  Regulator Start-up Characteristics,  $\rm V_{\rm CC}$  vs Vin

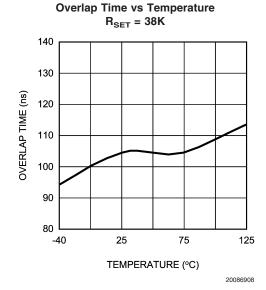




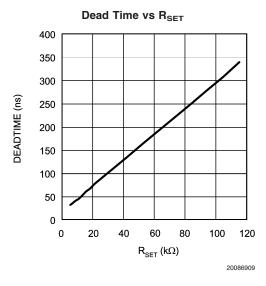


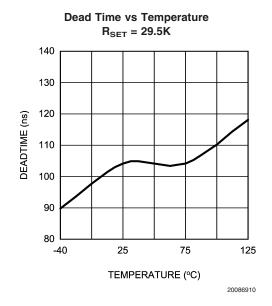




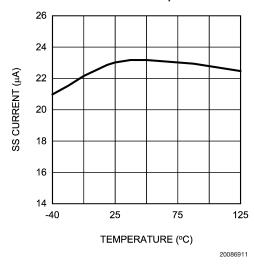


# Typical Performance Characteristics (Continued)





#### SS Pin Current vs Temperature



## **Detailed Operating Description**

The LM5025 PWM controller contains all of the features necessary to implement power converters utilizing the Active Clamp Reset technique. The device can be configured to control either a P-Channel clamp switch or an N-Channel clamp switch. With the active clamp technique higher efficiencies and greater power densities can be realized compared to conventional catch winding or RDC clamp / reset techniques. Two control outputs are provided, the main power switch control (OUT\_A) and the active clamp switch control (OUT\_B). The active clamp output can be configured for either a guaranteed overlap time (for P-Channel switch applications) or a guaranteed dead time (for N\_Channel applications). The two internal compound gate drivers parallel both MOS and Bipolar devices, providing superior gate drive characteristics. This controller is designed for highspeed operation including an oscillator frequency range up to 1MHz and total PWM and current sense propagation delays less than 100ns. The LM5025 includes a high-voltage start-up regulator that operates over a wide input range of 13V to 90V. Additional features include: Line Under Voltage Lockout (UVLO), softstart, oscillator UP/DOWN sync capability, precision reference and thermal shutdown.

## **High Voltage Start-Up Regulator**

The LM5025 contains an internal high voltage start-up regulator that allows the input pin (V<sub>IN</sub>) to be connected directly to the line voltage. The regulator output is internally current limited to 20mA. When power is applied, the regulator is enabled and sources current into an external capacitor connected to the  $V_{CC}$  pin. The recommended capacitance range for the  $V_{CC}$  regulator is  $0.1\mu F$  to  $100\mu F.$  When the voltage on the V<sub>CC</sub> pin reaches the regulation point of 7.6V and the internal voltage reference (REF) reaches its regulation point of 5V, the controller outputs are enabled. The outputs will remain enabled until V<sub>CC</sub> falls below 6.2V or the line Under Voltage Lock Out detector indicates that  $V_{\text{IN}}$  is out of range. In typical applications, an auxiliary transformer winding is connected through a diode to the  $\ensuremath{V_{\text{CC}}}$  pin. This winding must raise the  $V_{\text{CC}}$  voltage above 8V to shut off the internal start-up regulator. Powering V<sub>CC</sub> from an auxiliary winding improves efficiency while reducing the controller power dissipation.

The external  $V_{\rm CC}$  capacitor must be sized such that the capacitor and  $V_{\rm CC}$  self-bias will maintain a  $V_{\rm CC}$  voltage greater than 6.2V during the initial start-up. During a fault mode when the converter auxiliary winding is inactive, external current draw on the  $V_{\rm CC}$  line should be limited so the power dissipated in the start-up regulator does not exceed the maximum power dissipation of the controller.

An external start-up regulator or other bias rail can be used instead of the internal start-up regulator by connecting the  $V_{\rm CC}$  and the  $V_{\rm IN}$  pins together and feeding the external bias voltage into the two pins.

### **Line Under-Voltage Detector**

The LM5025 contains a line Under Voltage Lock Out (UVLO) circuit. An external set-point voltage divider from Vin to GND, sets the operational range of the converter. The divider must be designed such that the voltage at the UVLO pin will be greater than 2.5V when Vin is in the desired operating range. If the undervoltage threshold is not met, all functions of the controller are disabled and the controller remains in a low power standby state. UVLO hysteresis is accomplished with an internal 20uA current source that is switched on or off into the impedance of the set-point divider. When the UVLO threshold is exceeded, the current source is activated to instantly raise the voltage at the UVLO pin. When the UVLO pin voltage falls below the 2.5V threshold, the current source is turned off causing the voltage at the UVLO pin to fall. The UVLO pin can also be used to implement a remote enable / disable function. Pulling the UVLO pin below the 2.5V threshold disables the converter.

### **PWM Outputs**

The relative phase of the main (OUT\_A) and active clamp outputs (OUT\_B) can be configured for the specific application. For active clamp configurations utilizing a ground referenced P-Channel clamp switch, the two outputs should be in phase with the active clamp output overlapping the main output. For active clamp configurations utilizing a high side N-Channel switch, the active clamp output should be out of phase with main output and there should be a dead time between the two gate drive pulses. A distinguishing feature of the LM5025 is the ability to accurately configure either dead time (both off) or overlap time (both on) of the gate driver outputs. The overlap / deadtime magnitude is controlled by the resistor value connected to the TIME pin of the controller. The opposite end of the resistor can be connected to either REF for deadtime control or GND for overlap control. The internal configuration detector senses the connection and configures the phase relationship of the main and active clamp outputs. The magnitude of the overlap/dead time can be calculated as follows:

Overlap Time (ns) = 2.8 x R<sub>SET</sub> - 1.2 Dead Time (ns) = 2.9 x R<sub>SET</sub> +20 R<sub>SET</sub> in  $k\Omega$ , Time in ns

### PWM Outputs (Continued)

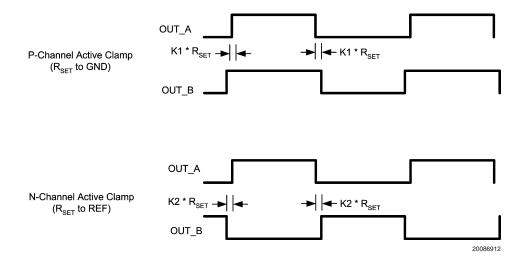
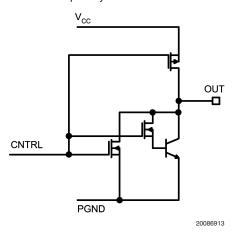


FIGURE 1.

## **Compound Gate Drivers**

The LM5025 contains two unique compound gate drivers, which parallel both MOS and Bipolar devices to provide high drive current throughout the entire switching event. The Bipolar device provides most of the drive current capability and provides a relatively constant sink current which is ideal for driving large power MOSFETs. As the switching event nears conclusion and the Bipolar device saturates, the internal MOS device continues to provide a low impedance to compete the switching event.

During turn-off at the Miller plateau region, typically around 2V - 3V, is where gate driver current capability is needed most. The resistive characteristics of all MOS gate drivers are adequate for turn-on since the supply to output voltage differential is fairly large at the Miller region. During turn-off however, the voltage differential is small and the current source characteristic of the Bipolar gate driver is beneficial to provide fast drive capability.



## **PWM Comparator**

The PWM comparator compares the ramp signal (RAMP) to the loop error signal (COMP). This comparator is optimized for speed in order to achieve minimum controllable duty cycles. The internal  $5k\Omega$  pull-up resistor, connected between

the internal 5V reference and COMP, can be used as the pull-up for an optocoupler. The comparator polarity is such that 0V on the COMP pin will produce a zero duty cycle on both gate driver outputs.

### **Volt Second Clamp**

The Volt x Second Clamp comparator compares the ramp signal (RAMP) to a fixed 2.5V reference. By proper selection of RFF and CFF, the maximum ON time of the main switch can be set to the desired duration. The ON time set by Volt x Second Clamp varies inversely with the line voltage because the RAMP capacitor is charged by a resistor connected to Vin while the threshold of the clamp is a fixed voltage (2.5V). An example will illustrate the use of the Volt x Second Clamp comparator to achieve a 50% duty cycle limit, at 200KHz, at a 48V line input: A 50% duty cycle at a 200KHz requires a 2.5 $\mu$ s of ON time. At 48V input the Volt x Second product is 120V x  $\mu$ s (48V x 2.5 $\mu$ s). To achieve this clamp level:

$$R_{FF} \times C_{FF} = V_{IN} \times T_{ON} / 2.5V$$
  
 $48 \times 2.5 \mu / 2.5 = 48 \mu$ 

Select C<sub>FF</sub> = 470pF

 $R_{FF} = 102k\Omega$ 

The recommended capacitor value range for CFF is 100pF to 1000pF.

The  $C_{\text{FF}}$  ramp capacitor is discharged at the conclusion of every cycle by an internal discharge switch controlled by either the internal clock or by the V x S Clamp comparator, whichever event occurs first.

#### **Current Limit**

The LM5025 contains two modes of over-current protection. If the sense voltage at the CS1 input exceeds 0.25V the present power cycle is terminated (cycle-by-cycle current limit). If the sense voltage at the CS2 input exceeds 0.25V, the controller will terminate the present cycle, discharge the softstart capacitor and reduce the softstart current source to  $1\mu A.$  The softstart (SS) capacitor is released after being fully discharged and slowly charges with a  $1\mu A$  current source. When the voltage at the SS pin reaches approximately 1V,

#### Current Limit (Continued)

the PWM comparator will produce the first output pulse at OUT\_A. After the first pulse occurs, the softstart current source will revert to the normal 20µA level. Fully discharging and then slowly charging the SS capacitor protects a continuously over-loaded converter with a low duty cycle hiccup mode.

These two modes of over-current protection allow the user great flexibility to configure the system behavior in over-load conditions. If it is desired for the system to act as a current source during an over-load, then the CS1 cycle-by-cycle current limiting should be used. In this case the current sense signal should be applied to the CS1 input and the CS2 input should be grounded. If during an overload condition it is desired for the system to briefly shutdown, followed by softstart retry, then the CS2 hiccup current limiting mode should be used. In this case the current sense signal should be applied to the CS2 input and the CS1 input should be grounded. This shutdown / soft-start retry will repeat indefinitely while the over-load condition remains. The hiccup mode will greatly reduce the thermal stresses to the system during heavy overloads. The cycle-by-cycle mode will have higher system thermal dissipations during heavy overloads, but provides the advantage of continuous operation for short duration overload conditions.

In some systems it is possible utilize both modes concurrently, whereby slight overload conditions activate the CS1 cycle-by cycle mode while more severe overloading activates the CS2 hiccup mode. Operating both modes concurrently, requires that the slope of the inductor current be

sufficient to reach the CS2 threshold before the CS1 function turns off the main output switch. This requires a high dv/dt at the current sense pin. The signal must be fast enough to reach the second level threshold before the first threshold detector (CS1) turns off the gate driver. Excessive filtering on the CS pin, an extremely low value current sense resistor or an inductor that does not saturate with excessive loading may prevent the second level threshold from ever being reached.

A small RC filter, located near the controller, is recommended for each of the CS pins. Each CS input has an internal FET which discharges the current sense filter capacitor at the conclusion of every cycle, to improve dynamic performance. This same FET remains on an additional 50ns at the start of each main switch cycle to attenuate the leading edge spike in the current sense signal.

The LM5025 CS comparators are very fast and may respond to short duration noise pulses. Layout considerations are critical for the current sense filter and sense resistor. The capacitor associated with the CS filter must be placed very close to the device and connected directly to the pins of the IC (CS and GND). If a current sense transformer is used, both leads of the transformer secondary should be routed to the filter network, which should be located close to the IC. If a sense resistor in the source of the main switch MOSFET is used for current sensing, a low inductance type of resistor is required. When designing with a current sense resistor, all of the noise sensitive low power ground connections should be connected together near the IC GND and a single connection should be made to the power ground (sense resistor ground point).



## **Oscillator and Sync Capability**

The LM5025 oscillator is set by a single external resistor connected between the RT pin and GND. To set a desired oscillator frequency (F), the necessary RT resistor can be calculated from:

 $RT = (5725/F)^{1.026}$ 

where F is in kHz and RT in  $k\Omega$ .

The RT resistor should be located very close to the device and connected directly to the pins of the IC (RT and GND). A unique feature of LM5025 is the ability to synchronize the oscillator to an external clock with a frequency that is either higher or lower than the frequency of the internal oscillator. The lower frequency sync frequency range is 80% of the free running internal oscillator frequency. There is no constraint on the maximum SYNC frequency. A minimum pulse width of 100ns is required for the synchronization clock . If the synchronization feature is not required, the SYNC pin should be connected to GND to prevent any abnormal interference . The internal oscillator can be completely disabled by connecting the RT pin to REF. Once disabled, the sync signal

will act directly as the master clock for the controller. Both the frequency and the maximum duty cycle of the PWM controller can be controlled by the SYNC signal (within the limitations of the Volt x Second Clamp). The maximum duty cycle (D) will be (1-D) of the SYNC signal.

## **Feed-Forward Ramp**

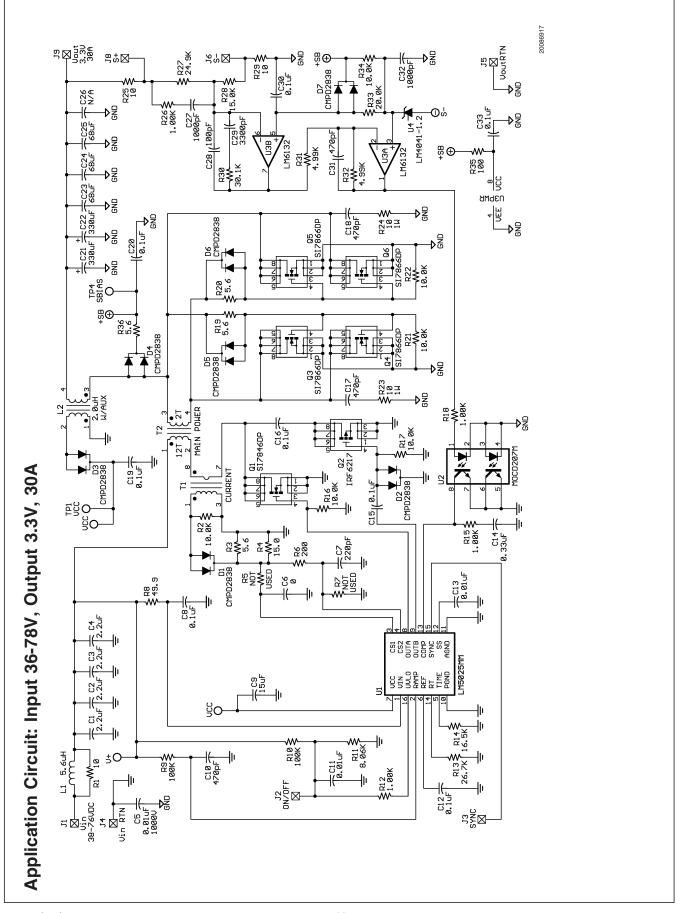
An external resistor ( $R_{FF}$ ) and capacitor ( $C_{FF}$ ) connected to  $V_{IN}$  and GND are required to create the PWM ramp signal. The slope of the signal at the RAMP pin will vary in proportion to the input line voltage. This varying slope provides line feedforward information necessary to improve line transient response with voltage mode control. The RAMP signal is compared to the error signal at the COMP pin by the pulse width modulator comparator to control the duty cycle of the main switch output. The Volt Second Clamp comparator also monitors the RAMP pin and if the ramp amplitude exceeds 2.5V the present cycle is terminated. The ramp signal is reset to GND at the end of each cycle by either the internal clock or the Volt Second comparator,which ever occurs first.

#### Soft-start

The softstart feature allows the power converter to gradually reach the initial steady state operating point, thus reducing start-up stresses and surges. At power on, a  $20\mu\text{A}$  current is sourced out of the softstart pin (SS) into an external capacitor. The capacitor voltage will ramp up slowly and will limit the COMP pin voltage and therefore the PWM duty cycle. In the event of a fault as determined by  $V_{CC}$  undervoltage, line undervoltage (UVLO) or second level current limit, the output gate drivers are disabled and the softstart capacitor is fully discharged. When the fault condition is no longer present a softstart sequence will be initiated. Following a second level current limit detection (CS2), the softstart current source is reduced to  $1\mu\text{A}$  until the first output pulse is generated by the PWM comparator. The current source returns to the nominal  $20\mu\text{A}$  level after the first output pulse (~1V at the SS pin).

#### **Thermal Protection**

Internal Thermal Shutdown circuitry is provided to protect the integrated circuit in the event the maximum junction temperature is exceeded. When activated, typically at  $165\,^{\circ}\text{C}$ , the controller is forced into a low power standby state with the output drivers and the bias regulator disabled. The device will restart after the thermal hysteresis (typically  $25\,^{\circ}\text{C}$ ). During a restart after thermal shutdown, the softstart capacitor will be fully discharged and then charged in the low current mode (1µA) similar to a second level current limit event. The thermal protection feature is provided to prevent catastrophic failures from accidental device overheating.



# **Physical Dimensions** inches (millimeters) unless otherwise noted 6.4 3.2 GAGE PLANE RECOMMENDED LAND PATTERN 0.25 O.2 CBA ALL LEAD TIPS SEATING PLANE SEE DETAIL A (0.9) ALL LEAD TIPS 0.1±0.05 TYP 14X 0.65 DIMENSIONS ARE IN MILLIMETERS DIMENSIONS IN ( ) FOR REFERENCE ONLY MTC16 (Rev D) Molded TSSOP-16 **NS Package Number MTC16** (16X 0.6) **C** RECOMMENDED LAND PATTERN (45° X0.2) --PIN 1 INDEX AREA 5 ± 0 . 1 # n n n n n m # # Ь 14X 0.5 SDA16A (Rev A) DIMENSIONS ARE IN MILLIMETERS Note: It is recommended that the exposed pad be connected to Pin 11 (AGND) 16-Lead LLP Surface Mount Package **NS Package Number SDA16A**

### **Notes**

#### LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### **BANNED SUBSTANCE COMPLIANCE**

National Semiconductor certifies that the products and packing materials meet the provisions of the Customer Products Stewardship Specification (CSP-9-111C2) and the Banned Substances and Materials of Interest Specification (CSP-9-111S2) and contain no "Banned Substances" as defined in CSP-9-111S2.



**National Semiconductor** Americas Customer Support Center

Email: new.feedback@nsc.com Tel: 1-800-272-9959

www.national.com

**National Semiconductor Europe Customer Support Center** Fax: +49 (0) 180-530 85 86

Email: europe.support@nsc.com
Deutsch Tel: +49 (0) 69 9508 6208
English Tel: +44 (0) 870 24 0 2171 Français Tel: +33 (0) 1 41 91 8790

**National Semiconductor** Asia Pacific Customer Support Center Email: ap.support@nsc.com **National Semiconductor** Japan Customer Support Center Fax: 81-3-5639-7507 Email: jpn.feedback@nsc.com Tel: 81-3-5639-7560

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.